

# Dual General Purpose Transistor

## NST3906DP6T5G

The NST3906DP6T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-963 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

### Features

- $h_{FE}$ , 100–300
- Low  $V_{CE(sat)}$ ,  $\leq 0.4$  V
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- This is a Pb-Free Device

### MAXIMUM RATINGS

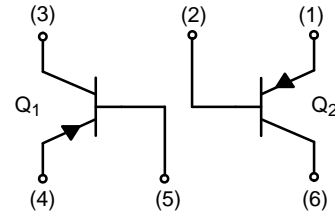
Rating	Symbol	Value	Unit
Collector - Emitter Voltage	$V_{CEO}$	–40	V
Collector - Base Voltage	$V_{CBO}$	–40	V
Emitter - Base Voltage	$V_{EBO}$	–5.0	V
Collector Current – Continuous	$I_C$	–200	mA
Electrostatic Discharge	HBM MM	ESD Class 2 B	

### THERMAL CHARACTERISTICS

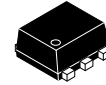
Characteristic (Single Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25$ °C Derate above 25 °C (Note 1)	$P_D$	240 1.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	520	°C/W
Total Device Dissipation $T_A = 25$ °C Derate above 25 °C (Note 2)	$P_D$	280 2.2	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	446	°C/W
Characteristic (Dual Heated) (Note 3)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25$ °C Derate above 25 °C (Note 1)	$P_D$	350 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	357	°C/W
Total Device Dissipation $T_A = 25$ °C Derate above 25 °C (Note 2)	$P_D$	420 3.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	297	°C/W
Junction and Storage Temperature Range	$T_J, T_{stg}$	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 @ 100 mm<sup>2</sup>, 1 oz. copper traces, still air.
2. FR-4 @ 500 mm<sup>2</sup>, 1 oz. copper traces, still air.
3. Dual heated values assume total power is sum of two equally powered channels.

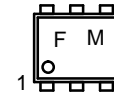


NST3906DP6T5G



SOT-963  
CASE 527AD

### MARKING DIAGRAM



F = Device Code  
M = Date Code

### ORDERING INFORMATION

Device	Package	Shipping†
NST3906DP6T5G	SOT-963 (Pb-Free)	8000/Tape & Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

# NST3906DP6T5G

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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### OFF CHARACTERISTICS

Collector-Emitter Breakdown Voltage (Note 4) ( $I_C = 1.0\text{ mA}$ , $I_B = 0$ )	$V_{(BR)CEO}$	-40	-	V
Collector-Base Breakdown Voltage ( $I_C = 10\text{ }\mu\text{A}$ , $I_E = 0$ )	$V_{(BR)CBO}$	-40	-	V
Emitter-Base Breakdown Voltage ( $I_E = 10\text{ }\mu\text{A}$ , $I_C = 0$ )	$V_{(BR)EBO}$	-5.0	-	V
Collector Cutoff Current ( $V_{CE} = 30\text{ Vdc}$ , $V_{EB} = 3.0\text{ Vdc}$ )	$I_{CEX}$	-	-50	nA

### ON CHARACTERISTICS (Note 4)

DC Current Gain ( $I_C = -0.1\text{ mA}$ , $V_{CE} = -1.0\text{ V}$ ) ( $I_C = -1.0\text{ mA}$ , $V_{CE} = -1.0\text{ V}$ ) ( $I_C = -10\text{ mA}$ , $V_{CE} = -1.0\text{ V}$ ) ( $I_C = -50\text{ mA}$ , $V_{CE} = -1.0\text{ V}$ ) ( $I_C = -100\text{ mA}$ , $V_{CE} = -1.0\text{ V}$ )	$h_{FE}$	60 80 100 60 30	- - 300 - -	-
Collector-Emitter Saturation Voltage ( $I_C = -10\text{ mA}$ , $I_B = -1.0\text{ mA}$ ) ( $I_C = -50\text{ mA}$ , $I_B = -5.0\text{ mA}$ )	$V_{CE(sat)}$	- -	-0.25 -0.4	V
Base-Emitter Saturation Voltage ( $I_C = -10\text{ mA}$ , $I_B = -1.0\text{ mA}$ ) ( $I_C = -50\text{ mA}$ , $I_B = -5.0\text{ mA}$ )	$V_{BE(sat)}$	-0.65 -	-0.85 -0.95	V

### SMALL-SIGNAL CHARACTERISTICS

Current-Gain – Bandwidth Product ( $I_C = 10\text{ mA}$ , $V_{CE} = 20\text{ Vdc}$ , $f = 100\text{ MHz}$ )	$f_T$	250	-	MHz
Output Capacitance ( $V_{CB} = -5.0\text{ V}$ , $I_E = 0\text{ mA}$ , $f = 1.0\text{ MHz}$ )	$C_{obo}$	-	4.5	pF
Input Capacitance ( $V_{EB} = -0.5\text{ V}$ , $I_E = 0\text{ mA}$ , $f = 1.0\text{ MHz}$ )	$C_{ibo}$	-	10.0	pF
Noise Figure ( $V_{CE} = -5.0\text{ V}$ , $I_C = -100\text{ }\mu\text{A}$ , $R_S = 1.0\text{ k}\Omega$ , $f = 1.0\text{ kHz}$ )	NF	-	4.0	dB

### SWITCHING CHARACTERISTICS

Delay Time	( $V_{CC} = -3.0\text{ V}$ , $V_{BE} = 0.5\text{ V}$ )	$t_d$	-	35	ns
Rise Time	( $I_C = -10\text{ mA}$ , $I_{B1} = -1.0\text{ mA}$ )	$t_r$	-	35	
Storage Time	( $V_{CC} = -3.0\text{ V}$ , $I_C = -10\text{ mA}$ )	$t_s$	-	250	ns
Fall Time	( $I_{B1} = I_{B2} = -1.0\text{ mA}$ )	$t_f$	-	50	

4. Pulse Test: Pulse Width  $\leq 300\text{ }\mu\text{s}$ ; Duty Cycle  $\leq 2.0\%$ .

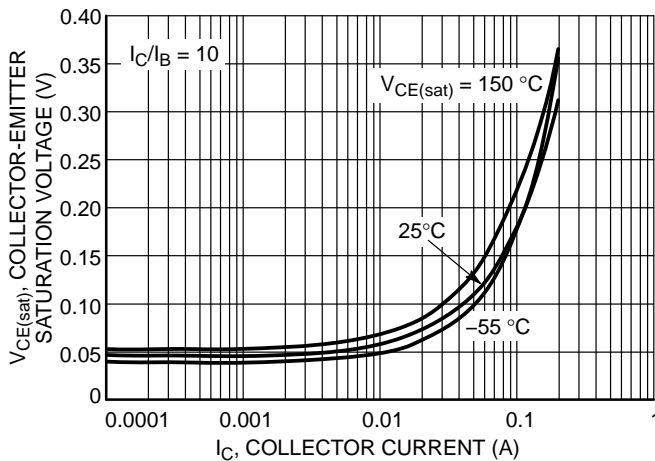


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

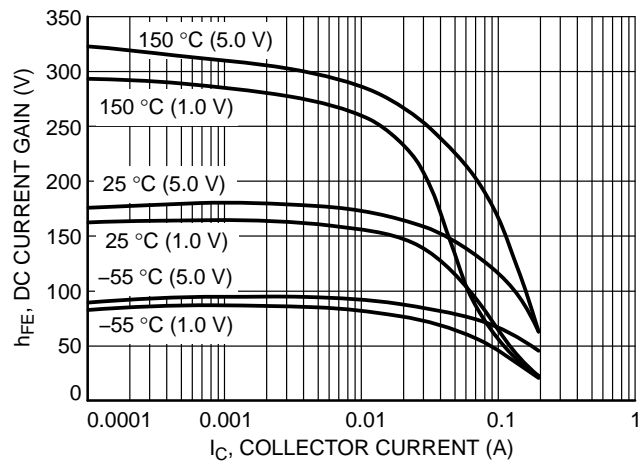
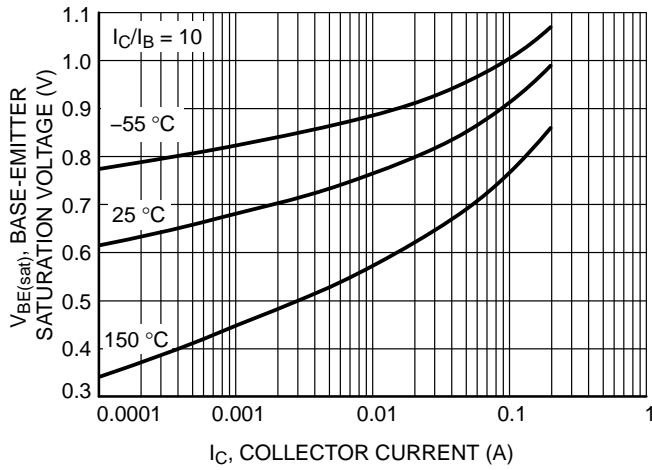
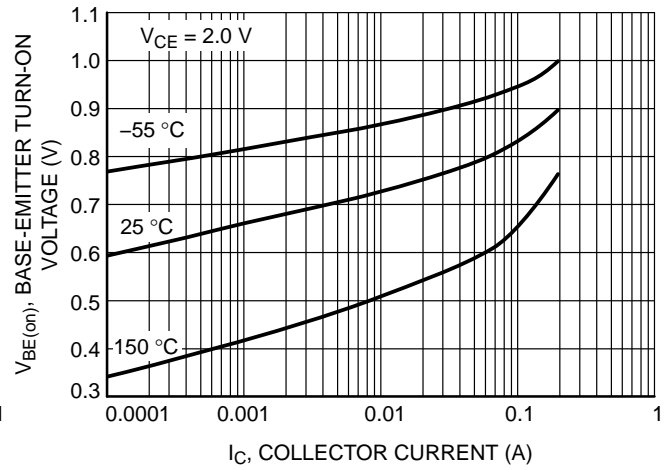


Figure 2. DC Current Gain vs. Collector Current

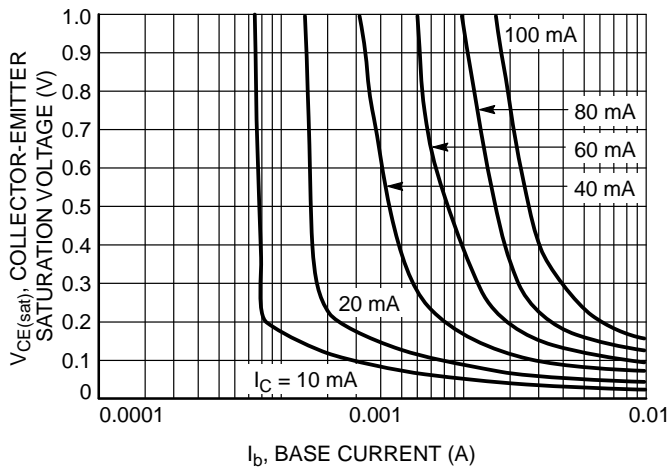
# NST3906DP6T5G



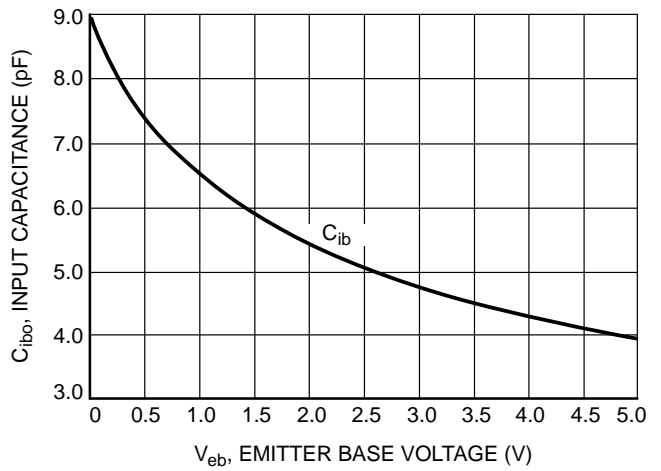
**Figure 3. Base Emitter Saturation Voltage vs. Collector Current**



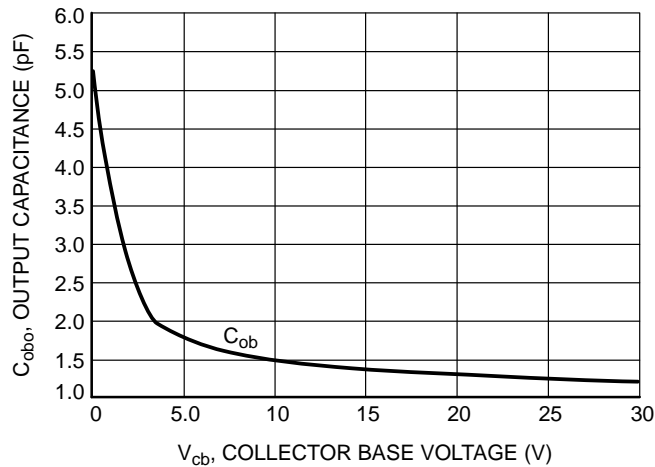
**Figure 4. Base Emitter Turn-On Voltage vs. Collector Current**



**Figure 5. Saturation Region**



**Figure 6. Input Capacitance**

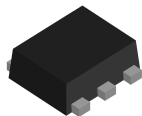


**Figure 7. Output Capacitance**

## NST3906DP6T5G

### REVISION HISTORY

Revision	Description of Changes	Date
2	Rebranded the Data Sheet to <b>onsemi</b> format.	6/18/2025

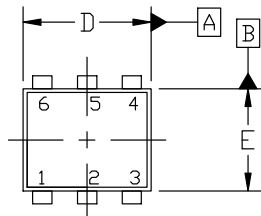


**SOT-963 1.00x1.00x0.37, 0.35P**  
CASE 527AD  
ISSUE F

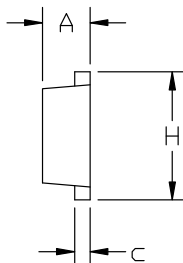
DATE 20 FEB 2024

NOTES:

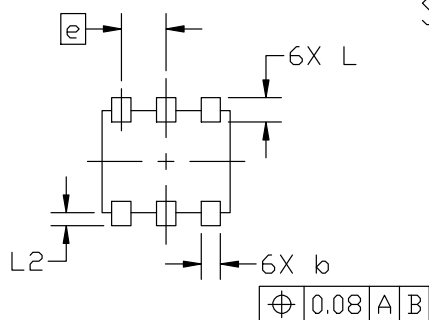
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.



TOP VIEW

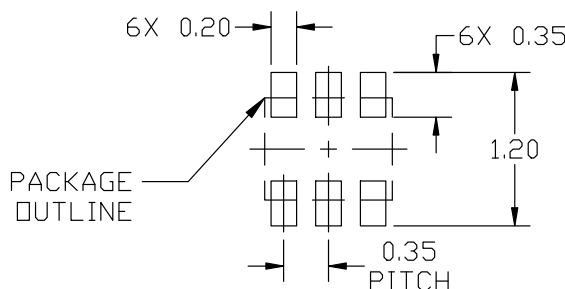


SIDE VIEW



BOTTOM VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.34	0.37	0.40
b	0.10	0.15	0.20
c	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
e	0.35 BSC		
H	0.95	1.00	1.05
L	0.19 REF		
L2	0.05	0.10	0.15



RECOMMENDED MOUNTING  
FOOTPRINT

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual, SOLDERRM/D.

STYLE 1:

- PIN 1. EMITTER 1  
2. BASE 1  
3. COLLECTOR 2  
4. EMITTER 2  
5. BASE 2  
6. COLLECTOR 1

STYLE 2:

- PIN 1. EMITTER 1  
2. EMITTER2  
3. BASE 2  
4. COLLECTOR 2  
5. BASE 1  
6. COLLECTOR 1

STYLE 3:

- PIN 1. CATHODE 1  
2. CATHODE 1  
3. ANODE/ANODE 2  
4. CATHODE 2  
5. CATHODE 2  
6. ANODE/ANODE 1

STYLE 4:

- PIN 1. COLLECTOR  
2. COLLECTOR  
3. BASE  
4. EMITTER  
5. COLLECTOR  
6. COLLECTOR

STYLE 5:

- PIN 1. CATHODE  
2. CATHODE  
3. ANODE  
4. ANODE  
5. CATHODE  
6. CATHODE

STYLE 6:

- PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. CATHODE  
5. CATHODE  
6. CATHODE

STYLE 7:

- PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. CATHODE  
5. ANODE  
6. CATHODE

STYLE 8:

- PIN 1. DRAIN  
2. DRAIN  
3. GATE  
4. SOURCE  
5. DRAIN  
6. DRAIN

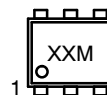
STYLE 9:

- PIN 1. SOURCE 1  
2. GATE 1  
3. DRAIN 2  
4. SOURCE 2  
5. GATE 2  
6. DRAIN 1

STYLE 10:

- PIN 1. CATHODE 1  
2. N/C  
3. CATHODE 2  
4. ANODE 2  
5. N/C  
6. ANODE 1

**GENERIC  
MARKING DIAGRAM\***



XX = Specific Device Code  
M = Month Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>SOT-963 1.00x1.00x0.37, 0.35P</b>	<b>PAGE 1 OF 1</b>

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